

IEEE 802.3da SPMD TF Plenary meeting March 2021

Prepared by Peter Jones

Presentations posted at:

<https://www.ieee802.org/3/da/index.html>

Agenda/Admin - Chad Jones

All times in Pacific Time (PT)

March 10, 2021

7:00am: The Chair reviewed the agenda in

https://www.ieee802.org/3/da/public/031021/8023da_agenda_031021.pdf. The Chair asked if there were any corrections or additions to the agenda. There being no corrections or additions, the agenda stands approved.

The Chair asked if anyone hasn't had a chance to review the minutes for February 24, 2021. None responded. The Chair asked if there were any change to be made to the February 24, 2021 minutes. None responded. The February 24, 2021 minutes were approved by unanimous consent.

7:07am: Call for patents was made, no one responded.

7:11am: opening agenda slides complete. The meeting moves on to presentations.

Presentations/Discussion.

7:12am: LLDP - Traffic Pattern Overview for 802.3da Single Pair Multidrop

Jason Potterf, Cisco Systems, Inc.

7:21am: presentation done, start of Q&A.

7:27am: Q&A done.

7:28am: Dynamic PLCA Node ID Assignment

Piergiorgio Beruto, Canova Tech

7:57am: presentation done, start of Q&A.

8:09am: Q&A done.

8:09am: SPE Multidrop Enhancements Mixing Segment Baseline Proposals

Chris DiMinico, MC Communications/PHY-SI LLC/SenTekse/Panduit

Bob Voss, Panduit

Paul Wachtel, Panduit

8:35am: presentation done, start of Q&A.

8:58am: Q&A closed for today.

Final presentation (Suggested Interpretation of Objective 4 , Jason Potterf, Cisco Systems, Inc.) deferred to next meeting.

8:59am: Closing remarks

9:01am: Meeting in Recess

Next meeting: March 17, 2021, 7:00am PT.

Meeting closed – 9:02am PT

March 10 Attendees (from IMAT & Webex)

Name	Employer	Affiliation	IMAT	WEBEX
Aekins, Rob	Legrand	Legrand	x	x
Alhammami, Talal		Volkswagen Ag	x	x
Aller, Harry		Innovative Lighting	x	x
Aono, Michikazu	Yazaki Corporation	Yazaki Corporation	x	x
Aronson, Joseph	Texas Instruments Incorporated	Texas Instruments Inc.	x	x
Baggett, Tim	Microchip Technology, Inc.	Microchip Technology, Inc.	x	x
Beaudoin, Denis	Texas Instruments Incorporated	Texas Instruments Incorporated	x	x
Beruto, Piergiorgio	Canova Tech S.r.l.	Canova Tech Srl	x	x
Boyer, Rich	Aptiv - Signal and Power Solutions	Aptiv Signal and Power Solutions	x	x
Brandt, David	Rockwell Automation	Rockwell Automation	x	x
Breneisen, Michael	Telebyte	Telebyte		x
Brychta, Michal	Analog Devices Inc.	Analog Devices Inc.	x	x
Buchanan, Rory	ON Semiconductor	ON Semiconductor	x	x
Carlson, Steven	High-Speed Design Inc.	Robert Bosch GmbH	x	x
Chang, Jae-Yong	Keysight	Keysight		x
Chang, Yung-Le		Realtek Semiconductor Corp.	x	x
Cuesta, Emilio		TE Connectivity	x	x
Dawson, Fred	Chemours Canada Company	Chemours Canada Company	x	x
Dearing, Mark	Leviton Manufacturing Co.	Leviton Manufacturing Co.	x	x
DiBiao, Eric	TE Connectivity	TE Connectivity	x	x
Diminico, Christopher	M C Communications, LLC	Panduit Corp.	x	x
Downey, Walter	Dialog	Dialog		x
Feyh, German	Broadcom Corporation	Broadcom Corporation	x	x
Fritsche, Matthias	HARTING Technologie Gruppe	HARTING Electronics GmbH	x	x
Frosch, Richard	Phihong USA Inc,	Phihong USA Inc,	x	x
Fung, Hon Wai		Marvell Semiconductor, Inc.	x	x
gianordoli, stefan		GG-group	x	
Goergen, Joel	Cisco Systems, Inc.	Cisco Systems, Inc.		x
Graber, Steffen	Pepperl+Fuchs SE	Pepperl+Fuchs SE	x	x
Hartmann, Stephan	Siliconally GmbH	Siliconally GmbH	x	x
Hess, David	CORD DATA	Cord Data / Cord Data	x	x
Huszak, Gergely	Self	KONE	x	x
ingrassia, alessandro	Canova Tech	Canova Tech	x	x
Islinger, Tobias	Infineon Technologies AG	Infineon Technologies AG	x	x
Jones, Chad	Cisco Systems, Inc.	Cisco Systems, Inc.	x	x
Jones, Peter	Cisco Systems, Inc.	Cisco Systems, Inc.	x	x
Kabra, Lokesh	Synopsys, Inc.	Synopsys, Inc.	x	x
Kagami, Manabu	Nagoya Institute of Technology	Nagoya Institute of Technology (NITech)	x	x
Kim, Dongok		HKMC	x	x
Koczwara, Wojciech	Rockwell Automation	Rockwell Automation	x	x
Konewko, Sebastian	Rockwell Automation	Rockwell Automation		x
Lackner, Hans	QoSCom GmbH	QoSCom - Quality in Communications - GmbH	x	x
Laubach, Mark	IEEE member / Self Employed	IEEE member / Self Employed	x	x
Law, David	Hewlett Packard Enterprise	Hewlett Packard Enterprise	x	x
Lewis, Jon	Dell Technologies	Dell Technologies	x	x

Maguire, Valerie	The Siemon Company	The Siemon Company	x	x
Matheus, Kirsten	BMW Group	BMW Group	x	x
McCarthy, Mick	Analog Devices Inc.	Analog Devices Inc.	x	x
Mcclellan, Brett	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.	x	x
Molina, Isaac	Analog Devices Inc.	Analog Devices Inc.		x
Mueller, Thomas	Rosenberger	Rosenberger	x	x
New, Anthony	Prysmian Cables & Systems	Prysmian Cables & Systems	x	x
Oliver, Doug	Ford	Ford		x
Paul, Michael	Analog Devices Inc.	Analog Devices	x	x
Pekar, Arkadiy	Microchip Technology, Inc.	Microchip Technology, Inc.		x
Pohl, Christopher	Beckhoff Automation	Beckhoff Automation	x	x
Potterf, Jason	Cisco Systems, Inc.	Cisco Systems, Inc.	x	x
Renteria, Victor	Bel Fuse	Bel Fuse	x	x
Rettig, Thomas	Beckhoff Automation	Beckhoff Automation	x	x
Savi, Olindo	Hubbell Incorporated	Hubbell Incorporated	x	x
Schneider, Ken	Telebyte	Telebyte		x
Secchiero, Elia	Canova Tech S.r.l.	Canova Tech S.r.l.	x	x
Shiino, Masato	FURUKAWA ELECTRIC	FURUKAWA ELECTRIC	x	x
Stewart, Heath	Analog Devices Inc.	Analog Devices Inc.	x	x
Thompson, Geoffrey	GraCaSI S.A.	INDEPENDENT	x	x
Tremblay, David	Hewlett Packard Enterprise	Hewlett Packard Enterprise	x	x
Tu, Mike	Broadcom Corporation	Broadcom Corporation	x	x
Vanderlaan, Paul	UL LLC	UL LLC	x	x
Voss, Robert	Panduit Corp.	Panduit Corp.	x	x
Voza, Viliam		ON Semiconductor	x	x
Wade, Scott	WadeLux Limited	DiiA	x	x
Wendt, Matthias	Signify	Signify		x
Withey, James	Fluke Corporation	Fluke Corporation	x	x
Wu, Peter	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.	x	x
Xu, Dayin	Rockwell Automation	Rockwell Automation	x	x
YANG, Yumeng	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd	x	x
Zimmerman, George	CME Consulting	CME Consulting/ADI, APL Group, CommScope, Cisco Systems, Marvell, and SenTekse	x	x

March 17, 2021

7:00am: The Chair reviewed the agenda in

https://www.ieee802.org/3/da/public/031021/8023da_agenda_031021.pdf.

7:04am: opening agenda slides complete. The meeting moves on to presentations.

Presentations/Discussion.

7:04am: Suggested Interpretation of Objective 4, Jason Potterf, Cisco Systems, Inc.

7:09am: presentation done, start of Q&A.

7:20am: Q&A done.

SPE Multidrop Enhancements Mixing Segment Baseline Proposals

7:23am: SPE Multidrop Enhancements Mixing Segment Baseline Proposals review

Chris DiMinico, MC Communications/PHY-SI LLC/SenTekse/Panduit

Bob Voss, Panduit

Paul Wachtel, Panduit

7:33am: presentation done, start of Q&A.

7:42am: Q&A done.

7:42am: SPE Multidrop Enhancements Mixing Segment Baseline Motions PREVIEW

Chris DiMinico, MC Communications/PHY-SI LLC/SenTekse/Panduit

Bob Voss, Panduit

Paul Wachtel, Panduit

8:01am: presentation done, start of Q&A.

8:17am: Q&A done.

8:18am: DPLCA Baseline PREVIEW

Piergiorgio Beruto, Canova Tech

8:45am: presentation done, start of Q&A.

8:55am: Q&A done.

8:55am: Closing remarks

8:59am: Meeting closed

Next meeting: March 24, 2021, 7:00am PT.

Meeting closed – 9:02am PT

March 17 Attendees (from IMAT & Webex)

Name	Employer	Affiliation	IMAT	Webex
Aekins, Rob	Legrand	Legrand	x	x
Alhammami, Talal		Volkswagen Ag	x	x
Aller, Harry		Innovative Lighting	x	x
Aono, Michikazu	Yazaki Corporation	Yazaki Corporation	x	x
Aronson, Joseph	Texas Instruments Incorporated	Texas Instruments Inc.	x	x
Baggett, Tim	Microchip Technology, Inc.	Microchip Technology, Inc.	x	x
Beaudoin, Denis	Texas Instruments Incorporated	Texas Instruments Incorporated	x	x
Beruto, Piergiorgio	Canova Tech S.r.l.	Canova Tech Srl	x	x
Boyer, Rich	Aptiv - Signal and Power Solutions	Aptiv Signal and Power Solutions	x	x
Brandt, David	Rockwell Automation	Rockwell Automation	x	x
Brychta, Michal	Analog Devices Inc.	Analog Devices Inc.	x	x
Buchanan, Rory	ON Semiconductor	ON Semiconductor	x	x
Buckmeier Brian	Bel Stewart	Bel Stewart		x
Carty, Clark	Cisco Systems, Inc.	Cisco Systems, Inc.	x	x
Chang, Yung-Le		Realtek Semiconductor Corp.	x	x
Cuesta, Emilio		TE Connectivity	x	x
Dawson, Fred	Chemours Canada Company	Chemours Canada Company	x	x
Deandrea, John	Finisar Corporation	Finisar Corporation	x	x
Dearing, Mark	Leviton Manufacturing Co.	Leviton Manufacturing Co.	x	x
DiBiao, Eric	TE Connectivity	TE Connectivity		x
DiMinico, Chris	M C Communications, LLC	Panduit Corp.		x
Downey, Walter	Dialog	Dialog		x
Eyal, Massad	Valens Semiconductor	Valens Semiconductor	x	
FAn, DAWEI	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd	x	
Fritsche, Matthias	HARTING Technologie Gruppe	HARTING Electronics GmbH	x	x
Frosch, Richard	Phihong USA Inc,	Phihong USA Inc,	x	x

Fung, Hon Wai		Marvell Semiconductor, Inc.	x	x
gianordoli, stefan		GG-group	x	
Graber, Steffen	Pepperl+Fuchs SE	Pepperl+Fuchs SE	x	x
Griffiths, Scott	Rockwell Automation	Rockwell Automation		x
Heck, Howard	Intel Corporation	Intel Corporation	x	x
Hess, Dave	Cord Data	Cord Data		x
Hua Chuang, Keng	HPE	HPE		x
Huszak, Gergely	Self	KONE	x	x
ingrassia, alessandro	Canova Tech	Canova Tech	x	x
ISHIBE, KAZUHIKO	Anritsu Company	Anritsu Company	x	
Islinger, Tobias	Infineon Technologies AG	Infineon Technologies AG	x	x
Isono, Hideki	Fujitsu Optical Components Limited	Fujitsu Optical Components Limited	x	x
Jimenez, Andy	Anixter Inc.	Anixter Inc.		x
Jones, Chad	Cisco Systems, Inc.	Cisco Systems, Inc.	x	x
Jones, Peter	Cisco Systems, Inc.	Cisco Systems, Inc.	x	x
Kabra, Lokesh	Synopsys	Synopsys		x
Kagami, Manabu	Nagoya Institute of Technology	Nagoya Institute of Technology (NITech)	x	x
Kobayashi, Shigeru	AIO Core	AIO Core	x	
Koczwara, Wojciech	Rockwell Automation	Rockwell Automation	x	x
Konewko, Sebastian	Rockwell Automation	Rockwell Automation		x
Kumada, Taketo	Yazaki Corporation	Yazaki Corporation	x	
Lackner, Hans	QoSCom GmbH	QoSCom - Quality in Communications - GmbH	x	x
Latchman, Ryan	MACOM	MACOM	x	
Maguire, Valerie	The Siemon Company	The Siemon Company	x	x
Marques, Flavio	FURUKAWA ELECTRIC	FURUKAWA ELECTRIC	x	x
Matheus, Kirsten	BMW Group	BMW Group	x	x
McCarthy, Mick	Analog Devices Inc.	Analog Devices Inc.	x	x
Meier, Gabriel		Self	x	x
Mueller, Thomas	Rosenberger	Rosenberger	x	x
Muller, Shimon	Axalume, Inc.	Axalume, Inc.	x	x
Nakagawa, Hideki		AGC Inc.	x	
NIIHARA, YOSHIHIRO	Fujikura Ltd.	Fujikura Ltd.	x	x
Nordman, Bruce	LBL	LBL		x
Oliver, Doug	Ford	Ford		x
Paul, Michael	Analog Devices Inc.	Analog Devices	x	x
Peker, Arkadiy	Microchip Technology, Inc.	Microchip Technology, Inc.		x
Pohl, Christopher	Beckhoff Automation	Beckhoff Automation	x	x
Potterf, Jason	Cisco Systems, Inc.	Cisco Systems, Inc.	x	x
Powell, William	INDEPENDENT	INDEPENDENT	x	x
Ramesh, Sridhar	MaxLinear	MAXLINEAR INC	x	
Reed, McKenzie	HARTING	HARTING Electronics GmbH		x
Renteria, Victor	Bel Stewart	Bel Stewart		x
Rettig, Thomas	Beckhoff Automation	Beckhoff Automation	x	x
Savi, Olindo	Hubbell Incorporated	Hubbell Incorporated	x	x
Schneider, Ken	Telebyte	Telebyte		x
Secchiero, Elia	Canova Tech S.r.l.	Canova Tech S.r.l.	x	x
Shiino, Masato	FURUKAWA ELECTRIC	FURUKAWA ELECTRIC	x	x
Stewart, Heath	Analog Devices Inc.	Analog Devices Inc.	x	x
Tracy, Nathan	TE Connectivity	TE Connectivity	x	x
Tu, Mike	Broadcom Corporation	Broadcom Corporation	x	x
Vanderlaan, Paul	UL LLC	UL LLC	x	x
Voss, Robert	Panduit Corp.	Panduit Corp.	x	x
Wade, Scott	WadeLux Limited	DiiA	x	x
Wendt, Matthias	Signify	Signify		x
Withey, James	Fluke Corporation	Fluke Corporation	x	x
Wu, Peter	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.	x	x

Xu, Dayin	Rockwell Automation	Rockwell Automation	x	x
YANG, Yumeng	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd	x	
Young, James	CommScope, Inc.	CommScope	x	x
Zimmerman, George	CME Consulting	CME Consulting/ADI, APL Group, CommScope, Cisco Systems, Marvell, and SenTekse	x	x